



Major Ratings and Characteristics

$I_{F(AV)}$	1.0 A
I_{FSM}	40 A
V_F	0.40 V
$T_j \text{ max.}$	150 °C



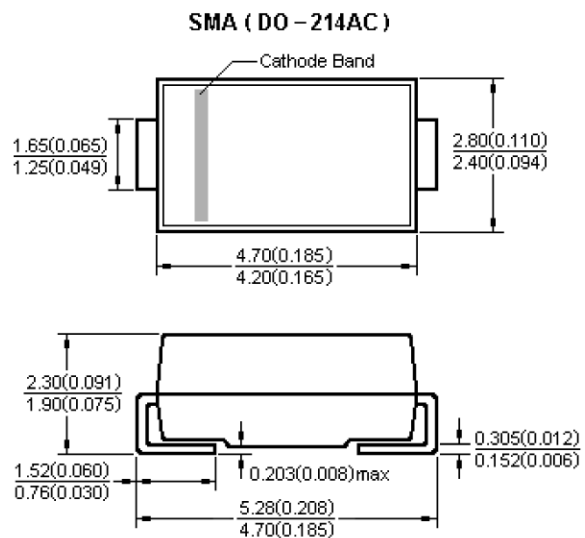
SMA (DO-214AC)

Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Date

- **Case:** JEDEC DO-214AC molded plastic body over passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end



Dimensions in millimeters and (inches)

Maximum Ratings & Thermal Characteristics & Electrical Characteristics

($T_A = 25\text{ °C}$ unless otherwise noted)

	Symbol	SL12	SL13	SL14	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	V
Maximum RMS voltage	V_{RMS}	28			V
Maximum DC blocking voltage	V_{DC}	40			V
Maximum average forward rectified current	$I_{F(AV)}$	1			A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	40			A
Maximum instantaneous forward voltage at 1.0A(Note1)	V_F	0.40			V
Maximum DC reverse current $T_A = 25\text{ °C}$ at Rated DC blocking voltage $T_A = 100\text{ °C}$	I_R	1.0 5.0			mA
Voltage rate of change (rated V_R)	dv/dt	10000			V/ μ s
Thermal resistance from junction to ambient(Note2)	$R_{\theta JA}$	88			°C/W
Operating junction and storage temperature range	T_J, T_{STG}	- 65 to +150			°C

Note1:Pulse Test with PW =300 μ sec, 1% Duty Cycle.

Note2:Mounted on P.C. Board with 5.0mm² (.013mm thick) copper pad areas.



Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

